



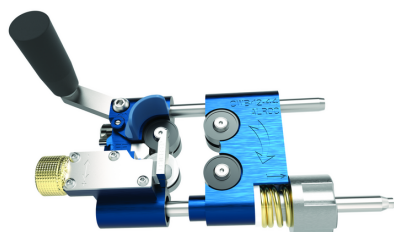
See online
technical sheet

/ CWB/12-44

Tool to remove bonded semiconductor with chamfer on the semiconductor cutback

/ Standards

- ENEDIS



/ Use

The CWB/12-44 enables the user to remove the bonded semicon with a chamfer on the semiconductor cutback

/ Advantages

- No silicon needed
- Cutting depth with 1/10 mm increments
- No clamp stopper needed
- Le temps de ponçage requis est très faible, voire quasiment superflu

/ Areas of activity



Cable & Connections



Substation



Electrical distribution



Industry

/ Technical specifications

- Specific tools : Cable tools
- Cable tools : Cable tools
- For network cables : HTA
- Packaging : Carton box
- Height (mm) : 74
- Max diameter (mm) : 44
- Mini diameter (mm) : 12
- Cut deepness (mm) : 1.8
- Chamfer angle (°) : 13
- Limit stop : None
- Remining length of semi conductor (MIN) (mm) : 25
- Length (mm) : 185
- Width (mm) : 103
- Weight (g) : 525

/ Spare parts

	Reference	Designation
	LCWB-FEP-V	Blade for bonded semi-conductor 13° + screws

/ Associated products

	Reference	Designation
	PG3HTA/2020	Pliers for MV cable outer sheath
	PG3HTA/2828	Pliers for MV cable outer sheath
	MF2/45	Multifunction tool for outer sheath and insulation
	PG3HTA/3035	PG3HTA/3035
	BRMRD1E	Insulation remover 14 - 40 mm
	PG3HTA/2530	Pliers for MV cable outer sheath
	GRI	Scraper for semiconductor residues